38510/MACH IV

High-Reliability Microelectronics Procurement Specifications

MIL-STD-883

CONTENTS

REVISIONS

CLASSIFICATION (MAJOR/MINOR)	DATE CODE EFFECTIVITY	LTR	DESCRIPTION	DATE	APPROVED
Major	7040	A	Incorporate MIL-M-38510 and Revision Notice 2 of MIL-STD-883	8/15/70	
Major	7239	B	Incorporate Revision Notice 3 and 4 of MIL-STD-883 and Revision A of MIL-STD-38510	9/1/72	
Major	7401	C	Incorporate revised Level IV (SNH) processing with inclusion of recorded electrical data with delta requirements; incorporate technological criteria in Table III for precap of complex circuits.	1/1/74	
Minor	7518	D	Incorporate Revision A of MIL-STD-883 and provisions for MOS LSI and CMOS devices	4/15/75	
Minor	7628	E	Incorporate Revision C of MIL-M-38510 and MIL-STD-883 Revision A, Notice 2	6/15/76	

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES:
ANGLES ± 1°
3 PLACE DECIMAL ±.010
2 PLACE DECIMAL ±.02
INTERPRET DWG. IN ACCORDANCE WITH STD. DESCRIBED IN MIL-STD-100
MATERIAL:

DR C. E. [illegible] DATE 9/22/69
CHK [illegible] 10/17/69
ENGR [illegible] 10/20/69
QUALITY CONTROL [illegible] 10/20/69
CRA MGR. J. D. Adams 10/21/69
DESIGN ACTIVITY RELEASE DEPARTMENT MANAGER, TTL [illegible]
CIRCUITS DIVISION MANAGER [illegible]

TEXAS INSTRUMENTS INCORPORATED
SEMICONDUCTOR CIRCUITS DIVISION DALLAS, TEXAS

TITLE
MICROELECTRONICS, HIGH RELIABILITY PROCUREMENT SPECIFICATION (MIL-STD 38510/883)

SIZE	CODE IDENT NO.	DRAWING NO.
A	01295	38510/MACH IV PROGRAM

SCALE | REV D | SHEET

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38510/MACH IV PROGRAM

1.0 SCOPE

1.1 This specification establishes standards for materials, workmanship, performance capabilities, identification, and processing of high-reliability monolithic integrated circuits.

1.2 Intent

The intent of this document is such as to recognize that quality and reliability are *built* into, not *tested* into, a product. There is no specification or screening procedure that can substitute for inherent, built-in reliability. However, it must be realized that irrespective of lot quality, there will always be some small percentage of devices that are subject to early failure (infant mortality). A well engineered screening procedure will eliminate most, if not all, of these early failures. Secondly, the screening and acceptance testing described herein will also serve to demonstrate, with a high degree of statistical confidence, that the required levels of quality and reliability have, in fact, been built into the product.

2.0 APPLICABLE DOCUMENTS

2.1 The following specifications and standards, of the issue in effect on the date of invitation for bids or request for proposal, form a part of this specification to the extent specified herein:

2.2 Specifications

9

Military

MIL-M-55565	Microcircuits, Packaging of
MIL-M-38510	Microcircuits devices, general specification for

2.3 Standards

Military

MIL-STD-105	Sampling Procedures and Tables for Inspection by Attributes
MIL-STD-883	Test Methods and Procedures for Microelectronics
MIL-STD-790	Reliability Assurance Program for Electronic Parts Specification
MIL-STD-1276	Leads, Weldable, for Electronic Components Parts
MIL-STD-1313	Microelectronics Terms and Definitions

Detail Specifications

SNXXXX (Bipolar) TMSXXXX (MOS LSI) TFXXXX (CMOS)	Detail Specification for a Particular Part Type (e.g., Manufacturer's Data Sheet)

2.4 Precedence of Documents

For the purpose of interpretation, in case of any conflicts, the following order of precedence shall apply:

a)	Purchase Order	—The purchase order shall have precedence over any referenced specification.
b)	Detail Specification	—The detail specification shall have precedence over this specification and other referenced specifications.
c)	This Specification	—This specification shall have precedence over all referenced specifications.
d)	Referenced Specifications	—Referenced Specifications shall apply to the extent specified herein.

2.5 Federal and/or military specifications and standards required shall be obtained from the usual government sources.

9

3.0 GENERAL REQUIREMENTS

The individual item requirements shall be as specified herein and in accordance with the applicable detail specification. In the event of any conflict between the requirements of this specification and the detail specification, the latter shall govern. The static and dynamic electrical performance requirements of the integrated circuits plus absolute maximum ratings and test methods shall be as specified in the detail specifications.

3.1.1 Definitions

a)	LTPD	Lot Tolerance Percent Defective shall be as defined by MIL-M-38510.
b)	λ	Lambda, stated in percent per 1000 hours as defined by MIL-M-38510.
c)	MRN	Minimum reject number as defined by MIL-M-38510.
d)	Production Lot	For the purpose of this specification, a production lot shall be defined per MIL-M-38510.
e)	Inspection Lot	An inspection lot shall be as defined in MIL-M-38510.
f)	C	Acceptance number as defined by MIL-M-38510.

3.1.2 Terms and Definitions

Terms and definitions shall be as defined in MIL-STD-1313.

3.1.3 Classification of Requirements

The requirements for the integrated circuits are classified herein as follows:

9

Requirement	Paragraph
Process Conditioning, Testing and Screening	3.2
Qualification	3.3
Design and Construction	3.4

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3.2 Process Conditioning, Testing and Screening

Three levels of screening and quality assurance for integrated circuits are provided for in this specification. Process conditioning, testing and screening shall be as specified in 4.3 and the applicable figure for the appropriate quality assurance level stated on the purchase order and defined as follows:

SCREENING LEVEL	PART NUMBER PREFIX			APPLICABLE FLOW CHART
	BIPOLAR	CMOS	MOS LSI	
38510/883 Class A (Level IV)	SNH	Not Avail.	Not Avail.	Figure 4
38510/883 Class B (Level III)	SNC	TFC		Figure 3
			SMC	Figure 2
38510/883 Class C (Level I)	SNM	TFM	Not Avail.	Figure 1

3.3 Qualification

Vendor qualification for delivery of integrated circuits to this specification shall be as specified in paragraph 4.2.

3.4 Design and Construction

Integrated circuit design and construction shall be in accordance with the requirements specified herein and in the applicable detail specification.

3.4.1 Topography

Integrated circuits furnished under this specification shall have topography information available for review by procuring activity. The information made available shall provide sufficient data for thorough circuit design, application, performance, and failure analysis studies.

3.4.1.1 Monolithic Die Topography

An enlarged photograph or drawing (to scale) with a minimum magnification of 80 times the die (chip) size showing the topography of elements formed on the silicon monolithic die shall be available for review. This shall be identified with the specific detail integrated circuit part-type in which it is used and the applicable detail specification.

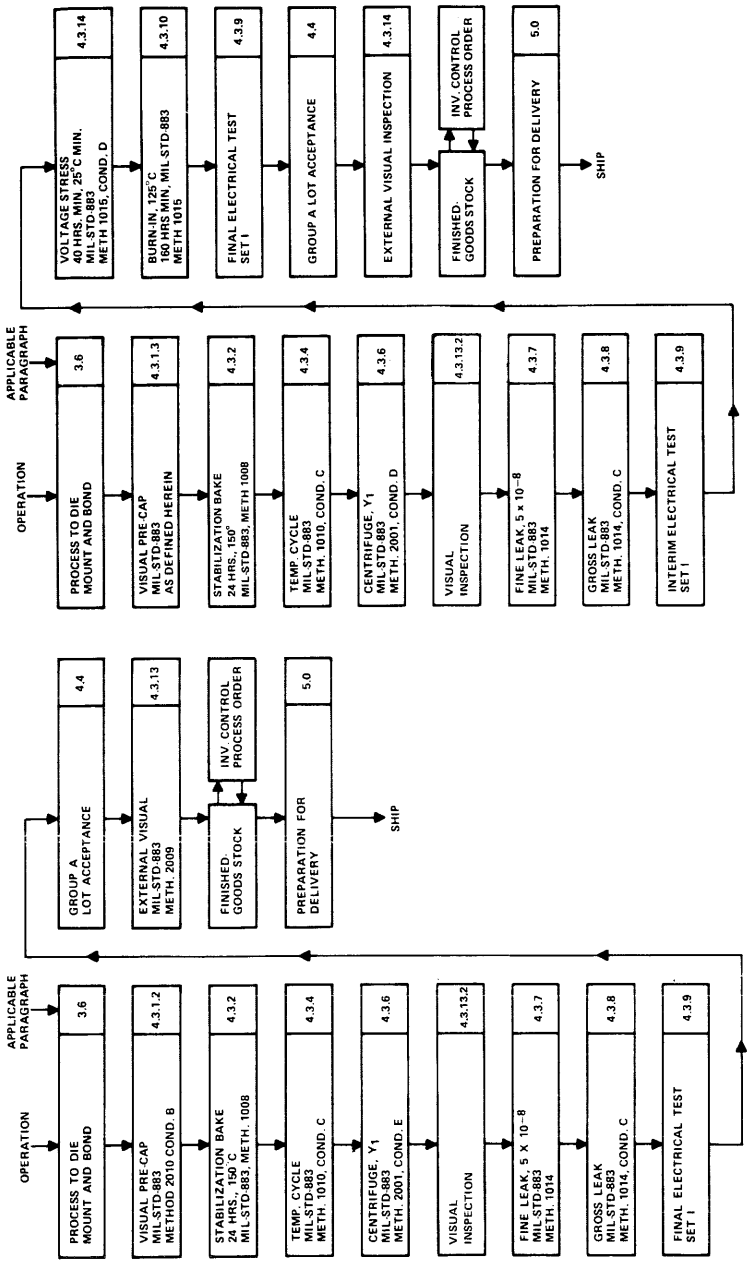

FIGURE 1–FLOW CHART FOR 38510 CLASS C LEVEL I

FIGURE 2–FLOW CHART FOR MOS LSI
38510 CLASS B (LEVEL III SMC)

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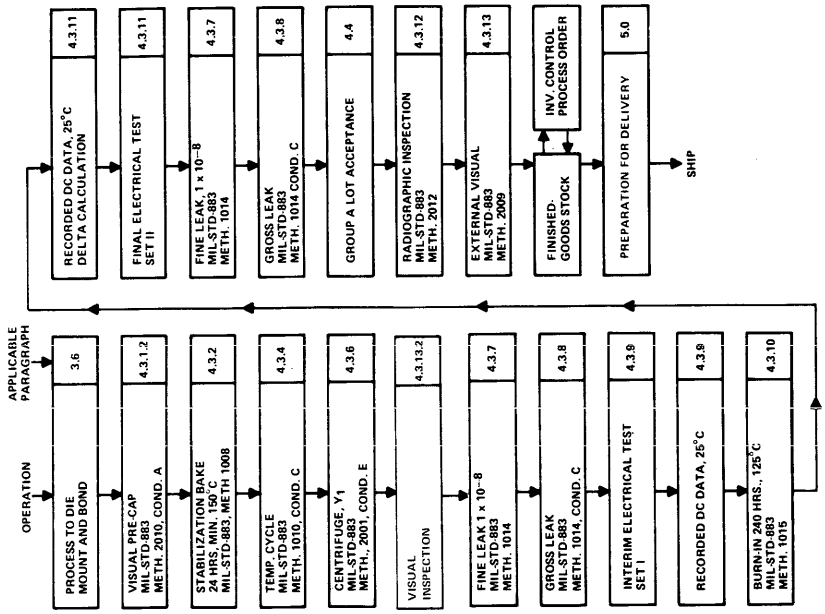

FIGURE 4–FLOW CHART FOR 38510 CLASS A LEVEL IV

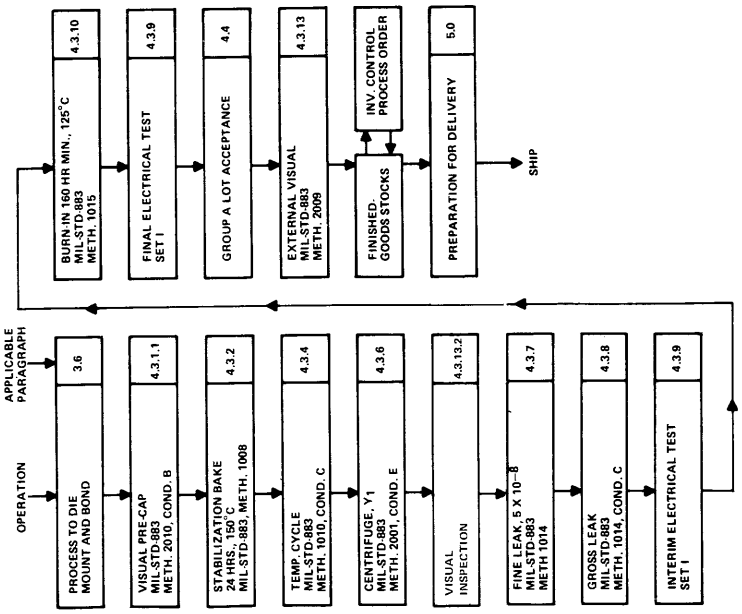

FIGURE 3–FLOW CHART FOR 38510 CLASS B LEVEL III

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3.4.1.2 Die Intraconnection Pattern

An enlarged photograph or drawing (to scale) with a minimum magnification of 80 times the die (chip) size showing the specific intraconnection pattern utilized to intraconnect the elements in the circuit. This shall be in the same scale as the die topography 3.4.1.1 so that the elements utilized and those not being used can easily be determined.

3.4.2 Materials

Materials shall be inherently non-nutrient to fungus and shall not blister, crack, outgas, soften, flow or exhibit other immediate or latent defects that adversely affect storage, operation or environmental capabilities of integrated circuits.

3.4.2.1 Material Selection

Materials selected for use in the construction of the integrated circuits shall be chosen for maximum suitability for the application. This shall include consideration of the best balance for:

a) Electrical performance

b) Thermal compatibility and conductivity

c) Chemical stability including resistance to deleterious interactions with other materials

d) Metallurgical stability with respect to adjacent materials and change in crystal configuration

e) Maximum stability with regard to continued uniform performance through the specified environmental conditions and life.

3.4.2.2 Foreign Materials

No lacquer, grease, paste, desiccant or other similar foreign encapsulant or coating material shall be included in the circuit enclosure nor applied to any part of the internal circuit assembly.

3.4.3 Mechanical

3.4.3.1 Case

Each integrated circuit shall be securely mounted and hermetically sealed within a case designed and constructed to conform to the outline and physical dimensions shown in the detailed specification.

3.4.3.2 Interconnections

Interconnections within the integrated circuit case shall be minimized and there shall be no wire crossovers. Circuit intraconnections by means of wire jumpers shall not be used. (See Note 6.2)

3.4.3.3 Leads

Lead material, construction, and outline shall be as specified on the detail specification and shall be capable of meeting the solderability test of MIL-STD-883, Method 2003. (See note 6.4).

3.4.3.3.1 Lead Size

Lead outline and dimensions shall be as specified in the detail specification.

3.4.3.3.2 Lead Surface Condition

Leads shall be free of the following defects over their entire length when inspected under a minimum of 4X magnification:

a) Foreign materials adhering to the leads such as paint, film, deposits and dust. Where adherence of such foreign materials is in question, leads may be subjected to a clean, contaminant-free (e.g., oil, dust, etc.), filtered air stream (suction or expulsion) of 88 feet per second maximum, or a wash/rinse as necessary and reinspected.

b) Nicks, cuts, scratches or other surface defacing defects which expose the base metal.

3.4.3.3.3 Lead Straightness

Leads shall be aligned within a 0.050-inch diameter, 0.050-inch length cylinder concentric to the point of lead emergence from the case and the X-axis (the axis parallel to the lead axis). Along the remaining lead length, there shall be no unspecified bend whose radius is less than 0.10 inch and no twist whose angle is greater than 30° (ribbon leads, only).

3.4.3.3.4 Preformed Leads

Preformed leads, when specified, shall be in accordance with the detail specification. The part number of the integrated circuit shall remain as specified in the applicable detail specification or purchase order, the applicable suffix designation shall appear on the purchase order but shall not be marked on the device.

3.4.3.3.5 Carriers (Mech-Pak Carrier)

Carrier-matrix assemblies consisting of individually mounted integrated circuits shall be furnished when so specified by purchase order. The individual carriers shall have provisions for use with automatic test equipment contacts. Devices supplied "clipped-out" of the Mech-Pak Carrier shall be supplied in the Barnes Carrier type 029-188 or equivalent. (Applicable to Flat Packs only.)

3.5 Marking of Integrated Circuits

3.5.1 Legibility

All marking shall be permanent in nature and remain legible when subjected to specified operating, storage, and environmental requirements. All markings shall be insoluble in standard solvents such as trichlorethylene, water and xylene.

3.5.2 Marking Details

Marking of the integrated circuits shall be located as follows unless otherwise specified in the detail specification:

a) TO-99, TO-100, and similar "can" cases shall be marked on the top of the case. Where space limitations exist, the side of the case may be used.

b) Flat Packs shall be marked on the top of the case. Where space limitation exists, the bottom of the package may be utilized as necessary. As a minimum the top of the package shall show the manufacturer's identification mark or symbol, the device part number, date code, and pin 1 orientation mark (where applicable).

c) Dual-in-line plug-in packages shall be marked in the same manner as flat packs.

3.5.3 Required Device Marking

a) Index point indicating the starting point for numbering of leads shall be as indicated in the detail specification. The indexing point may be a tab, color dot, or other suitable indicator.

b) Manufacturer's identification mark or symbol.

c) A lot date code indicating the week of initial submission for screening or inspection. The date code shall be as follows:

1) EIA four-digit date code, the first two numbers shall be the last two digits of the year, the last two numbers shall indicate the calendar week.

2) EIA three-digit date code (when limited by space available), the first number shall be the last digit of the year, the last two numbers shall indicate the calendar week.

d) Manufacturer's part number defining circuit type and applicable MIL-STD-883 screening level and MIL-M-38510 product assurance level as defined in paragraph 3.2.

e) Individual device serial number is required for Class A (SNH).

f) A dot to indicate acceptance by Radiographic inspection.

NOTE:

When a color dot is used to identify pin one, the radiographic inspection acceptance dot shall be placed on the bottom of the package.

g) Country of origin shall be per U.S. Customs codes.

3.6 Product Assurance

The manufacturer shall establish and maintain a reliability assurance program that complies with the basic intent of MIL-STD-790. Furthermore, it is intended that each integrated circuit delivered shall be free of any defect in design, material, manufacturing process, testing and handling, which would degrade or otherwise limit its performance when used within the specified limits.

3.6.1 Visual and Mechanical Examination

Integrated circuits shall be examined to verify that material, design, construction, physical dimensions, marking and workmanship are in accordance with the specified acceptance criteria.

3.6.2 Test Equipment

The manufacturer shall prepare and maintain a current list, by name and drawing number or other unique identification, of test equipment used in the manufacturing and testing of devices submitted for acceptance inspection under this specification. This list shall be made available to the procuring activity representative upon request.

3.6.3 Process Controls

Each integrated circuit shall be constructed by manufacturing processes which are under the surveillance of the manufacturer's Quality Control department. The processes shall be monitored and controlled by use of statistical techniques in accordance with published specifications and procedures. The manufacturer shall prepare and maintain suitable documentation (such as quality control manuals, inspection instructions, control charts, etc.) covering all phases of incoming part and material inspection and in-process inspections required to assure that product quality meets the requirements of this specification. The

procuring activity may verify, with the permission of and in the company of the manufacturer's designated representative, that suitable documentation exists and is being applied. Information designated as proprietary by the manufacturer will be made available to the procuring activity or its representative only with the written permission of the manufacturer.

Process control is recognized as being vital to the concept of "built-in" quality. The process control program shall include a scanning electron microscope (SEM) monitor program for evaluating the metal integrity over oxide step and oxide step contour. The SEM analysis will be defined in a Quality & Reliability Assurance document.

3.6.4 Production Changes

The manufacturer shall advise the procuring activity of the time at which any major change(s) in production or QC methods or documentation become effective during the period of device production for delivery against any given purchase order referencing this specification.

3.7 Workmanship

Integrated circuits shall be manufactured and processed in a careful and workmanlike manner, in accordance with the production processes, workmanship instructions, inspection and test procedures, and training aids prepared by the manufacturer in fulfillment of the reliability assurance program established by paragraph 3.6.

3.7.1 Personnel Certification

The manufacturer shall be responsible for training, testing and certification of personnel involved in producing integrated circuits. Training shall be commensurate and consistent with the requirements of this specification and in conformance to the basic intent of MIL-STD-790. Training aids in the form of satisfactory criteria shall be available for operator and inspector review at any time.

3.7.2 Personnel Evaluation

The supplier shall maintain a continuous evaluation of the proficiency of personnel concerned with production and inspection. Retraining of an operator or inspector shall be required when this evaluation establishes that a degree of proficiency necessary to meet the requirements of this specification is not being exercised.

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3.7.3 Rework provisions

3.7.3.1 Rework

All rework on micorcircuits manufactured under this specification shall be accomplished in accordance with paragraph 3.7.1 of MIL-M-38510 as defined herein.

3.7.3.2 Rebonding

Rebonding shall be in accordance with MIL-M-38510, as defined herein (see Note 6.5)

3.8 Performance Capabilities

The integrated circuits delivered to this specification shall be designed to be capable of meeting the environmental requirements specified in Table ii. The manufacturer need not perform these tests specifically for the contract or specification, but shall provide data which demonstrates the ability of the integrated circuits to pass the environmental tests. The data shall have been generated on devices from the same generic family as the circuits being supplied to this specification, and the package configuration shall be the same as for the delivered parts (i.e., Flat Pack, TO-100, etc.).

3.9 Quality and Reliability Assurance Program Plan

The manufacturer shall establish and implement a Quality and Reliability Assurance Program Plan that meets the intent of MIL-M-38510, Appendix A. Submission of the program plan to the procuring activity shall not be a requirement of this specification; however, the program plan shall be maintained by the manufacturer and shall be available for review by the procuring activity.

4.0 QUALITY ASSURANCE PROVISIONS

4.1 Responsibility for Inspection

Unless otherwise specified in the contract or purchase order, the manufacturer is responsible for the performance of all inspection requirements specified herein. Except as otherwise specified, the manufacturer may utilize his own facilities or any commercial laboratory acceptable to the procuring activity. The procuring activity may, at its discretion, perform any of the inspections set forth in the specification where such inspections are deemed necessary to assure supplies and services conform to prescribed requirements.

4.1.1 Inspection and Testing Procedures Coverage

Inspection and testing processes and procedures prepared in fulfillment of the reliability assurance program established per paragraph 3.6 shall be prescribed by clear, complete and current instructions. These instructions shall assure inspection and test of materials, work in process and completed integrated circuits as required by this specification. In addition, criteria for approval and rejection of materials and integrated circuits shall be included.

4.1.2 Inspection at Point of Delivery

The procuring activity may, at its discretion, reinspect any or all of the delivered parts excluding Groups B, C, and D destructive samples as defined by MIL-STD-883. All parts found to be defective, excluding devices exhibiting damage from use, may be returned to the manufacturer at the manufacturer's expense.

4.1.3 Inspection Records

The manufacturer shall maintain a reliability data and records library. This library shall have on file, for review by the procuring activity, records of examination, qualification test results, variables data (when required) and all other pertinent data generated on devices manufactured to this specification.

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4.1.4 Control of Procurement Sources

The manufacturer shall be responsible for assuring that all supplies and services conform to this specification, the detail specification and the manufacturer's procurement requirements.

4.1.4.1 Manufacturer's Receiving Inspection

Purchased supplies shall be subjected to inspection after receipt as necessary to ensure conformance to contract requirements. In selecting sampling plans, consideration shall be given to the controls exercised by the procurement source and evidence of sustained quality conformance.

4.1.4.2 The manufacturer shall provide procedures for withholding from use all incoming supplies pending completion of required tests or receipt of necessary certification or test records and their evaluation.

4.1.4.3 The manufacturer shall initiate corrective action with the procurement source depending upon the nature and frequency of receipt of nonconforming supplies.

4.1.5 Procuring Activity Quality Assurance Representative

The procuring activity, may, at its discretion, place quality assurance representatives in the manufacturer's plant as deemed necessary to assure conformance to contract requirements in any non-proprietary phase of design, fabrication, processing, inspection, and testing of the integrated circuits being produced. The manufacturer shall provide reasonable facilities and assistance for the safety and convenience of such personnel in the performance of their duties. Inspection and test procedures shall be made available for review by the quality assurance representative.

4.2 Qualification and Quality Conformance Inspection

4.2.1 Qualification

When specifically called out and funded on the purchase order or contract, the manufacturer's specific device qualification shall be based on compliance with the quality conformance test per Table III for MOS LSI devices. Qualification for other technologies shall be per Table I except that the testing will be to one LTPD level tighter than as defined in Table B-I of MIL-M-38510. For 38510 Class A (Level IV), qualification shall be per MIL-STD-883, Method 5005, Table IIa.

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4.2.1.2 Procedures and Definitions

4.2.1.2.1 Sampling Procedure

Device selection for the qualification procedure of 4.2.1 shall be based on a random sampling technique and will be selected from a generic family.

4.2.1.2.2 Generic Family

Electrically and structurally similar devices shall be said to comprise a generic family (e.g., TTL) if they meet the following criteria:

a) Are designed with the same basic circuit-element configuration such as TTL, TTL Schottky, DTL, CMOS, MOS metal-gate, or MOS silicon-gate, and differ only in the number or complexity of specified circuits that they contain. Generic family for linear circuits is defined by circuit function (e.g., op amp, comparator, etc.).

b) Are designed for the same supply, bias and signal voltage, and for input/output capability with each other under an established set of loading rules.

c) Are enclosed in housings (packages) of the same basic construction (e.g., hermetically sealed flat packages, dual-in-line ceramic, dual-in-line plastic) and outline, differing only in the number of active housing terminals included and/or utilized.

4.2.2 Quality Conformance Inspection

Quality conformance inspections (Groups B, C, and D) are per Tables I and II. Table II shall apply to MOS LSI and Table I to other technologies.

a) When specifically called out and funded on the purchase order or contract, the manufacturer shall perform the quality conformance inspections (Groups B, C, and D) on a lot-by-lot basis.

b) The manufacturer shall, upon request, make available for review the following generic quality conformance inspection and data:

Group B – To be performed every six weeks on each package type (a different number of pins constitutes a different package) at each assembly location.

Group C – To be performed every three months on each generic family as defined in 4.2.1.2.2a and b.

Group D – To be performed every six months on each package type (a different number of pins constitutes a different package) at each assembly location.

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4.2.2.1 Lot Acceptance Sampling

Statistical sampling for quality conformance inspections shall be in accordance with MIL-M-38510 Table B-I.

Group B samples shall be selected from sublots that have successfully completed all of the 100% processing steps specified on the applicable process flow chart.

4.2.2.2 Resubmission of Failed Lots

When any lot (paragraph 4.2.2.a) submitted for quality conformance inspection fails any subgroup requirement, it may be resubmitted a maximum of one time for that particular subgroup. This additional submission is permitted, provided an analysis is performed to determine the failure mechanism for each reject device in the subgroup, and that it is determined that the failures are due to one of the following:

a) Testing error resulting in electrical damage to devices

b) A defect that can effectively be removed by rescreening the lot

c) Random defects that do not reflect poor basic device designs or poor workmanship.

4.2.2.3 Early Shipments

When quality conformance inspection is being performed for a specific contract or purchase order, the accepted Group A devices that are awaiting shipment pending successful completion of Groups B, C, and D shall be stored and controlled by Quality Assurance. Under no circumstances shall such parts be shipped prior to the successful completion of the Group B tests.

4.2.2.4 Groups B, C, and D Test Data

All lot-by-lot data generated by Groups B, C, and D testing when specifically called out and funded on the purchase order, shall accompany the initial shipment of devices. This data shall consist, at a minimum, of the following:

a) Attributes data for Group B. Endpoints for the subgroups are visual per the applicable MIL-STD-883 test method.

b) Attributes data for Groups C and D. Endpoints for each subgroup are electrical test parameters as defined in Tables I and II.

4.2.2.5 Precedure in Case of Test Equipment Failure or Operator Error

Where an integrated circuit is believed to have failed as a result of faulty test equipment or operator error, the failure shall be entered in the test record which shall be retained for review along with a complete explanation verifying why the failure is believed to be invalid. If it is determined that the failure is invalid, a replacement integrated circuit from the same inspection lot may be added to the sample. The replacement integrated circuit shall be subjected to all those tests to which the discarded integrated circuit was submitted prior to its failure, and any remaining specified test to which the discarded integrated circuit was not subjected prior to its failure.

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4.3 Quality Assurance Processing, Methods and Procedures

This section establishes the test methods and conditions to be used for the 100% processing (screening) requirements specified by the applicable process flow chart.

4.3.1 Precap Visual Inspection

Each microcircuit shall be required to pass the appropriate precap visual inspection defined as follows. Precap Lot Acceptance shall be per paragraph 4.6.

4.3.1.1 38510 Class C (Level I) and 38510 Class B (Level III) devices shall be visually inspected in accordance with MIL-STD-883, Method 2010, Condition B.

4.3.1.2 38510A Class A (Level IV) devices (designated for NASA type applications) shall be visually inspected in accordance with MIL-STD-883, Method 2010, Condition A. (See notes 6.1.1.1 and 6.1.1.2.) (See notes under 6.1.2 for MOS LSI devices.)

4.3.1.3 Complex MSI and LSI circuits as defined in MIL-STD-883, Method 5004, paragraph 3.3 may be precap inspected per MIL-STD-883, Method 5004, paragraph 3.3.1 for 38510 Class B (Level III) and paragraph 3.3.2 for 38510 Class C (Level I).

4.3.2 Stabilization Bake

The purpose of this test is to determine the effect on microelectronic devices of baking at elevated temperatures without electrical stress applied. Test shall be performed in accordance with MIL-STD-883, Method 1008, Condition C.

4.3.3 Thermal Shock

The purpose of this test is to determine the resistance of the device to sudden exposure to extreme changes in temperature. Test shall be performed in accordance with MIL-STD-883, Method 1011, Condition A.

4.3.4 Temperature Cycle

This test is conducted for the purpose of determining the resistance of a part to exposures to extremes of high and low temperatures, and to the effect of alternate exposures to these extremes, such as would be experienced when equipment or parts are transferred to and from heated shelters in arctic areas. Test shall be performed in accordance with MIL-STD-883, Method 1010, Condition C, for a minimum of 10 cycles. For MSI and LSI comples devices as defined in MIL-STD-883, Method 5004, paragraph 3.3, 50 cycles may be used in lieu of alternate pre-cap visual inspection criteria.

4.3.5 (Deleted)

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4.3.6 Centrifuge (Constant Acceleration)

The centrifuge test is used to determine the effects on microelectronics devices of a centrifugal force. This test is designed to indicate structural and mechanical weaknesses not necessarily detected in shock and vibration tests. Test shall be performed in accordance with MIL-STD-883, Method 2002, Condition E for devices having 20 or less pins and Condition D for those having more than 20 pins.

4.3.7 Fine Leak Test

Each integrated circuit for 38510 Class C (Level I), 38510 Class B (Level III), and 38510 Class A (Level IV) screens shall be subject to a fine leak test in accordance with paragraph 4.3.7.1 or 4.3.7.2. The method shall be optional providing it is consistent with and capable of detecting the specified leak rate of the applicable process flow chart.

4.3.7.1 Helium Leak Test

Helium leak test shall be performed in accordance with MIL-STD-883, Method 1014, Condition A.

4.3.7.2 Radiflo Leak Test

Radiflo leak test shall be performed in accordance with MIL-STD-883, Method 1014, Condition B. Krypton 85 bomb pressure and dwell time are a function of the radioactivity level and shall be selected so as to conform to the equations given in Condition B.

4.3.8 Gross-Leak Test

Each integrated circuit for 38510 Class C (Level I), 38510 Class B, (Level III) and 38510 Class A (Level IV) screens shall be subjected to the appropriate gross-leak test of paragraph 4.3.8.1 or 4.3.8.2, or an approved equivalent. The manufacturer may, at his option, perform gross-leak testing after the Set I Electrical Tests of paragraph 4.3.9.

4.3.8.1 When specifically called out and funded on the purchase order or contract, units will be bombed 2 hours minimum at 30 psig in FC-78, or equivalent. Units will then be immersed in FC-40 or equivalent at +125°C ±5°C for 30 seconds minimum and observed for for a definite stream of bubbles, more than two large bubbles, or an attached bubble that grows in size, per MIL-STD-883, Method 1014, Condition C2.

4.3.8.2 Units will be immersed in FC-40 or equivalent at +125°C ± 5°C for 30 seconds minimum and observed for a definite stream of bubbles, or more than two large bubbles per MIL-STD-883, Method 1014, Condition C1.

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4.3.9 Final Electrical Test (Set I)

Each integrated circuit shall be required to pass the electrical requirements of the data sheet. The manufacturer shall also perform such additional testing necessary to assure the parts will meet the temperature extreme limits. MOS LSI memory devices will be 100% tested both at 25°C and at high temperature. Linear circuits will be 100% dc tested at high and low temperatures and 25°C.

When specifically called out and funded on the purchase order or contract, the manufacturer shall perform subgroups 2, 3, and 4 of paragraph 4.4 in accordance with Method 5004 of MIL-STD-883.

4.3.10 Burn-In

The burn-in screen is performed for the purpose of eliminating marginal devices and early-life failures. Device biasing shall be in accordance with MIL-STD-883 Method 1015, Conditions A, D, or E for Digital Circuits and Conditions B, C, or D for Linear Circuits. For 38510 Class B (Level III) devices, equivalent test conditions using the time/temperature acceleration factor of Condition F between the temperature range of 125°C to 150°C may be used. For 38510 Class B (Level III) MSI and LSI complex devices as defined in MIL-STD-883 paragraph 3.3.1, a 240 hour burn-in in lieu of alternate pre-cap visual inspection criteria per MIL-STD-883, Method 5004, paragraph 3.3.1 may be used.

4.3.11 Final Electrical Test (Set II)

Each 38510 Class A (Level IV) integrated circuit shall be required to pass the electrical requirements of the detail specifications. The following tests shall be performed as a minimum: dc parameters at maximum and minimum rated temperatures, and switching parameters at 25°C. In addition, each bipolar device shall have critical 25°C dc electrical parameters read and recorded by serial number and shall pass the following delta requirements:

PARAMETER	DELTA LIMIT
V_{OL}	±10% of detail specification limit
V_{OH}	±10% of detail specification limit
I_{IL}	±10% of detail specification limit
I_{IH}	±10% of detail specification limit

CMOS recorded parameters and delta limits will be defined by the manufacturer as required.

One copy of the pre-burn-in and post-burn-in recorded data with delta calculations shall be shipped with each lot. Data will not be available for the metal flat pack (T). See MIL-M-0038510, Class S. The manufacturer may, when deemed necessary, elect to perform additional electrical testing over and above the requirements stated herein.

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4.3.12 Radiographic Inspection (X-Ray)

Test shall be performed in accordance with MIL-STD-883, Method 2012. X-ray may be performed at any point after serialization at the manufacturer's option (see note 6.3).

4.3.13 External Visual Inspection

4.3.13.1 The purpose of this examination is to verify that materials, construction, marking, and general workmanship are as specified. Examination shall be in accordance with MIL-STD-883, Method 2009.

4.3.13.2 Visual inspection will be performed for catastrophic failures. Catastrophic failures are defined as missing leads, broken packages, and damaged lids.

4.3.14 Voltage Stress

Selected n-channel MOS LSI devices will be voltage stressed for 40 hours minimum at 25°C min per MIL-STD-883 Method 1015, Condition D.

4.4 Group A Conformance

Group A conformance shall consist of the electrical parameters in the manufacturer's data sheet. If an inspection lot is made up of a collection of sublots, each sublot shall conform to Group A, as specified.

SUBGROUP	LTPD (%) LEVEL I 38510C	LEVEL II	LEVEL III 38510B	LEVEL IV 38510A
Subgroup 1 25°C, dc	5	7	5	5
Subgroup 2 High Temperature, dc	10	10	7	5
Subgroup 3 Low Temperature, dc	10	10	7	5
Subgroup 4 Dynamic and Switching Tests @ 25°C	10	10	7	5

NOTES: Functional tests included in dc tests.
MOS LSI devices will be lot accepted at 25°C and high temperature.
The LTPD's of subgroups 1 and 2 will apply.

4.5 Certification

The manufacturer shall include a certificate of compliance with each shipment of parts if requested on the purchase order. This certificate shall indicate that all specified tests and requirements of this specification have been made or met, and that the lot of devices (identified by lot and/or batch number) is acceptable. The certificate shall bear the name and signature of the manufacturer's Quality Control representative, the date of acceptance or signing, and any pertinent notes as applicable.

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4.6 Precap Lot Acceptance

After each precap inspection the lot of devices shall be sampled by quality control and inspected for the specified visual criteria.

TABLE 1
QUALITY CONFORMANCE TEST (GROUPS B, C, D)

TEST	MIL-STD-883 METHOD	MIL-STD-883 CONDITION	CLASSES B, C LTPD
GROUP B 1/			
Subgroup 1 Physical dimensions	2016		2 devices (no failures)
Subgroup 2 a. Resistance to solvents	2015		3 devices (no failures)
b. Internal visual and mechanical	2014	Failure criteria from design and construction requirements of applicable procurement document.	1 device (no failures)
c. Bond strength 2/ (1) Thermocompression (2) Ultrasonic or wedge	2011	(1) Test condition D (2) Test condition D	15
Subgroup 3 Solderability 3/	2003	Soldering temperature of 260 ± 10°C.	15
GROUP C (Die Related Tests)			
Subgroup 1 Operating life test End point electrical parameters	1005	Test condition to be specified (1000 hours) As specified in the applicable device specification	5
Subgroup 2 Temperature cycling	1010	Test condition C	15
Constant acceleration	2001	Test condition E min. (see 3) Y_1 axis followed by one other axis X or Z.	
Seal (a) Fine (b) Gross 2/	1014	As applicable	
Visual examination	1/		
End-point electrical parameters		As specified in the applicable device specification	

1. Electrical reject devices from the same inspection lot may be used for all subgroups when end-point measurements are not required.
2. Test samples for bond strength may, at the manufacturer's option unless otherwise specified, be randomly selected following internal visual (precap) inspection specified in method 5004, prior to sealing.
3. All devices submitted for solderability test must have been through the temperature/time exposure specified for burn-in. The LTPD for solderability test applies to the number of leads inspected except in no case shall less than 3 devices be used to provide the number of leads required.

1. Visual examination shall be in accordance with method 1010.
2. When fluorocarbon gross-leak testing is utilized, test condition C_2 shall apply as minimum.

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TABLE 1
QUALITY CONFORMANCE TEST (GROUPS B, C, D)
(continued)

TEST	MIL-STD-883 METHOD	MIL-STD-883 CONDITION	CLASSES B, C LTPD
GROUP D (Package Related Test)			
Subgroup 1			
Physical dimensions	2016		15
Subgroup 2/1			
Lead integrity	2004	Test condition B2 (lead fatigue)	15
Seal	1014	As applicable	
(a) Fine 2/			
(b) Gross 3/			
Subgroup 3/4			
Thermal shock	1011	Test condition B as a minimum, 15 cycles minimum.	15
Temperature cycling	1010	Test condition C, 100 cycles minimum.	
Moisture resistance	1004		
Seal	1014	As applicable	
(a) Fine 2/			
(b) Gross 3/			
Visual examination	5/		
End point electrical parameters		As specified in the applicable device specification.	
Subgroup 4/4			
Mechanical shock	2002	Test condition B	15
Vibration variable frequency	2007	Test condition A	
Constant acceleration	2001	Test condition E (see 3)	
Seal	1014	As applicable	
(a) Fine 2/			
(b) Gross 3/			
Visual examination	6/		
End point electrical parameters	5005	Subgroups 1, 2, 3, and 7.	
Subgroup 5/1			
Salt atmosphere	1009	Test condition A. Omit initial conditioning	15
Visual examination	7/		

1. Electrical reject devices from the same production lot may be used for samples.
2. Condition A or B per paragraph 3.7 herein.
3. When fluorocarbon gross leak testing is utilized; test condition C2 shall apply as minimum.
4. Devices used in subgroup 3, "Thermal and Moisture Resistance", may be used in subgroup 4, "Mechanical".
5. Visual examination shall be in accordance with method 1010 or 1011 at a magnification of 5X to 10X.
6. Visual examination shall be performed in accordance with method 2007 for evidence of defects or damage to case, leads, or seals resulting from testing (not fixturing). Such damages shall constitute a failure.
7. Visual examination shall be in accordance with paragraph 3.3.1 of method 1009.

TABLE II
QUALITY CONFORMANCE TEST
MOS LSI CIRCUIT

TEST	MIL-STD-883 METHOD	CONDITIONS	LTPD
Subgroup 1			
Temperature Cycle	1010	Condition C	
Constant Acceleration	2001	Condition D[1], Y_1 Plane	
Electrical End Points	5005	Subgroup 1	15
Subgroup 2			
Operating Life	1005	Condition D, 500 Hrs. Minimum	
Electrical End Points	5005	Subgroup 1	10

1. Condition D for packages with more than 20 pins. Condition E for packages with 20 pins or less.

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TABLE III
MANUFACTURER'S QUALIFICATION PROCEDURE
MOS LSI CIRCUITS

TEST	MIL-STD-883 METHOD	MIL-STD-883 CONDITION	CLASSES B, C LTPD
GROUP B			
Subgroup 1			
Physical dimensions	2016		2 devices (no failures)
Subgroup 2			
a. Resistance to solvents	2015		3 devices (no failures)
b. Internal visual and mechanical	2014	Failure criteria from design and construction requirements of applicable procurement document.	1 device (no failures)
c. Bond strength 2/	2011		15
(1) Thermocompression		(1) Test condition D	
(2) Ultrasonic or wedge		(2) Test condition D	
Subgroup 3			
Solderability 3/	2003	Soldering temperature of 260 ±10°C.	15

1. Electrical reject devices from the same inspection lot may be used for all subgroups when end-point measurements are not required.
2. Test samples for bond strength may, at the manufacturer's option unless otherwise specified, be randomly selected following internal visual (precap) inspection specified in method 5004, prior to sealing.
3. All devices submitted for solderability test must have been through the temperature/time exposure specified for burn-in. The LTPD for solderability test applies to the number of leads inspected except in no case shall less than 3 devices be used to provide the number of leads required.

GROUP C (Die Related Tests)

Subgroup 1			
Operating life test	1005	T_A = 85°C, 1000 hours minimum	5
End point electrical parameters Subgroups 1, 2, 3, and 7	5005		
Subgroup 2			
Temperature cycling	1010	Test condition C	15
Constant acceleration	2001	Test condition E for package with $<$20 pins Test condition D for packages with $\geq$20 pins Y_1 axis followed by one other axis X or Z.	
Seal	1014	As applicable	
(a) Fine			
(b) Gross 2/			
Visual examination	1/		
End-point electrical parameters		As specified in the applicable device specification	

1. Visual examination shall be in accordance with method 1010.
2. When fluorocarbon gross-leak testing is utilized, test condition C_2 shall apply as minimum.

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TABLE III
MANUFACTURER'S QUALIFICATION PROCEDURE
MOS LSI CIRCUITS
(continued)

TEST	MIL-STD-883 METHOD	MIL-STD-883 CONDITION	CLASSES B, C LTPD
GROUP D (Package Related Test)			
Subgroup 1			
Physical dimensions	2016		15
Subgroup 2[1]			
Lead integrity	2004	Test condition B2 (lead fatigue)	15
Seal	1014	As applicable	
(a) Fine[2]			
(b) Gross[3]			
Subgroup 3[4]			
Thermal shock	1011	Test condition B as a minimum, 15 cycles minimum	15
Temperature cycling	1010	Test condition C, 100 cycles minimum.	
Moisture resistance	1004		
Seal	1014	As applicable	
(a) Fine[2]			
(b) Gross[3]			
Visual examination	[2] [5]		
End point electrical parameters		As specified in the applicable device specifications.	
Subgroup 4[4]			
Mechanical shock	2002	Test condition B	15
Vibration variable frequency	2007	Test condition A	
Constant acceleration	2001	Test condition E (see 3)	
Seal	1014	As applicable	
(a) Fine[2]			
(b) Gross[3]			
Visual examination	[3] [6]		
End point electrical parameters	5005	Subgroups 1, 2, 3, and 7.	
Subgroup 5[1]			
Salt atmosphere	1009	Test condition A. Omit initial conditioning	15
Visual examination	[5] [7]		

1. Electrical reject devices from the same production lot may be used for samples.
2. Condition A or B per paragraph 3.7 herein.
3. When fluorocarbon gross leak testing is utilized; test condition C2 shall apply as minimum.
4. Devices used in subgroup 3, "Thermal and Moisture Resistance", may be used in subgroup 4, "Mechanical".
5. Visual examination shall be in accordance with method 1010 or 1011 at a magnification of 5X to 10X.
6. Visual examination shall be performed in accordance with method 2007 for evidence of defects or damage to case, leads, or seals resulting from testing (not fixturing). Such damages shall constitute a failure.
7. Visual examination shall be in accordance with paragraph 3.3.1 of method 1009.

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5.0 PREPARATION FOR DELIVERY

5.1 Final Visual Shipping Inspection

Each lot of microcircuits and its associated documentation shall be sampled by Quality Control and visually inspected for the following:

a) Scratched, nicked or bent leads

b) Damaged header (packages)

c) All test data specified in section 4.0

d) Certificate of Compliance as specified in section 4.0

e) All other pertinent documentation required and specified by this specification.

5.2 Packing Requirements

Parts shall be packed in containers of the type, size, and kind commonly used which will ensure acceptance by common carriers and safe delivery at the destination and in accordance with MIL-M-55565, Level C, bulk pack. The containers shall be clearly marked with manufacturer's name or symbol.

5.3 Preservation and Package Identification

The package shall be marked with the following:

The country of origin if other than U.S.A.

Procuring activity parts number

Purchase order number

Material nomenclature

Quantity

Lot number

Date code

This information shall appear on the label or shall be directly marked on each container. Method is optional.

6.0 NOTES

6.1 Precap Visual Method 2010

The following criteria may be in conflict with the circuit design topology and construction techniques of some microcircuit manufacturers. Where such a conflict does exist, the inspection criteria listed herein may be waived. (Reference paragraph 3.0 of MIL-STD-883, Method 2010).

6.1.1 Preseal Visual Inspection, Test Condition B [38510 Class B (Level III) and 38510 Class C (Level I)].

6.1.1.1 Paragraph 3.2: a 20-PSI minimum blow-off prior to seal will be performed to meet the intent of a controlled environment.

6.1.1.2 For titanium-tungsten, gold, titanium-tungsten multilayered systems, the underlying metal is defined as the bottom titanium tungsten and the top layer is defined as gold.

6.1.2 Preseal Visual Inspection for MOS LSI devices (38510 Class B, level III SMC). When the alternate screening option of paragraph 3.3 of Method 5004 is applied, the following additional items are applicable:

6.1.2.1 Internal visual, Method 2010, Condition B: In addition to the changes indicated by paragraph 3.3.1 of Method 5004, the following additional clarifications and deletions are applicable as reflected in MIL-M-38510/235:

a) Metallization inspection shall be applicable to the top layer metal conductor (i.e., Al) and need not include "underlying conductors" such as poly-silicon.

b) Omit paragraphs 3.2.1.1 (b) through 3.2.1.1 (e), 3.2.1.2 (b) through 3.2.1.2 (e) and 3.2.3 (e) (Items 3.2.1.1 (f) and 3.2.3 (g) do not apply).

6.2 Interconnections

Circuit interconnections (metallization pattern) shall be designed so that no properly fabricated connection shall experience a current density greater than 5×10^5 amperes/cm^2, including allowances for worst-case conductor composition, normal production tolerances on design dimensions, and nominal thickness at critical areas such as contact windows.

6.3 X-Ray Method 2012

Paragraph 3.9.2.2a(2) and (3) delete and replace with: "Cause for rejection shall be a single void in the bar attachment material opening two adjacent sides and exceeding 50% of the length of one side and 100% of the length of the other side."

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6.4 Salt Atmosphere Test, Method 1009

Where package design considerations necessitate (such as 0.75-inch tip-to-tip metal flat packs), there may be a conformal coating applied prior to the salt atmosphere test.

6.5 Rebonding

Attempts to bond where only impressions have been made in the metal and where the bond did not make a physical attachment to the pad or post shall not be considered evidence of rebonding.

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